IPC/JEDEC J-STD-035
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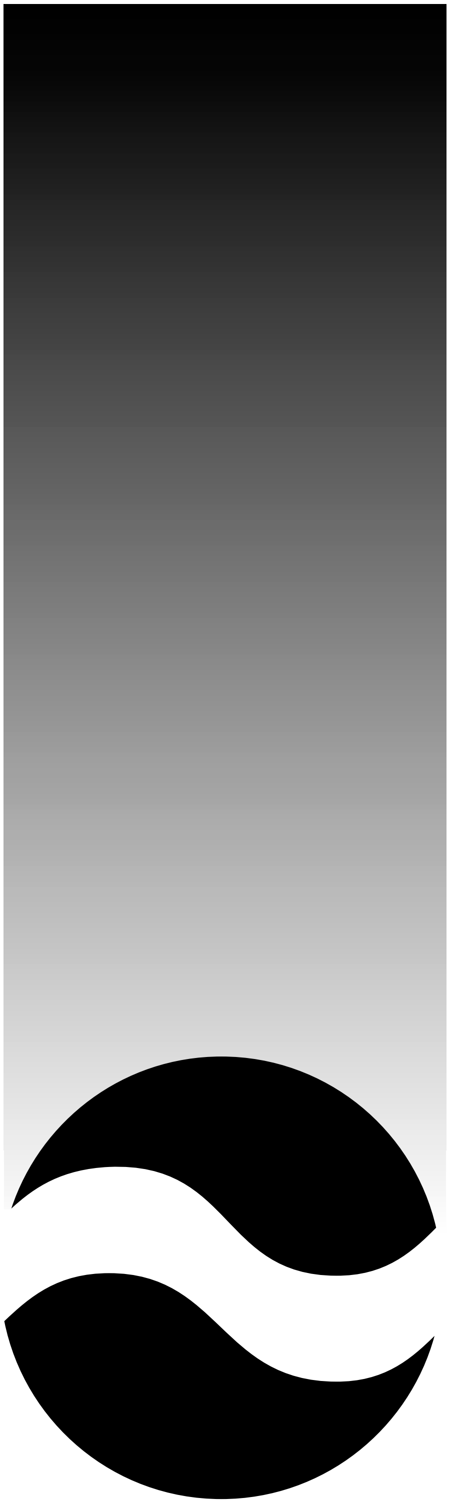

Acoustic Microscopy for Non-Hermetic Encapsulated Electronic Components

Supersedes IPC-SM-786
Supersedes IPC-TM-650, 2.6.22

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The material in this joint standard was developed by the EIA/JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the IPC Plastic Chip Carrier Cracking Task Group (B-10a)

The J-STD-035 supersedes IPC-TM-650, Test Method 2.6.22.

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IPC/JEDEC J-STD-035

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A joint standard developed by the EIA/JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the B-10a Plastic Chip Carrier Cracking Task Group of IPC

Users of this standard are encouraged to participate in the development of future revisions.

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